Statement of Materials, Construction

16L OPLGA -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Substrate	BT Resin	0.02351	BT Epoxy	Proprietary	0.01022	28.69409	43.45
				Solder Mask	Proprietary	0.00361	10.13043	15.34
				Cu	7440-50-8	0.00926	26.01289	39.39
				Au	7440-57-5	0.00032	0.90474	1.37
				Ni	7440-02-0	0.00011	0.29718	0.45
2	Die	Silicon Chip	0.000290	Si	7440-21-3	0.00029	0.81053	99.5
3	Die attach material	Conductive Epoxy	0.000270	Epoxy resin	Proprietary	0.00004	0.11376	15
				Ag	7440-21-3	0.00022	0.60674	80
				Diester	Proprietary	0.00001	0.03792	5
				Functionalized Ester	Proprietary	0.00000	0.00000	0
4	Wire	Gold	0.0015000	Au	7440-57-5	0.00150	4.21306	99.99
5	Encapsulation	Epoxy Resin	0.01003	Bisphenol A type	25068-38-6	0.00542	15.21404	54
				Epoxy resin	2451-62-9	0.00160	4.50787	16
				Tetra Hydrophthalic Anhydride	85-43-8	0.003009	8.45225	30
				Halogenated Flame Retardants	Proprietary	0.00000	0.00000	0
Total Package weight			0.03560					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%